



SPIRE-RAL-NOT-001822

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To: Horst, Guy, Carsten, Jean-Louis, Dave, Chris

From: John Delderfield

cc: Eric, Doug, Bruce, Matt, Renato.

Forthcoming IID-B Annex 1 Unit ICDs Version 7

At the recent Spire / Industry interface meeting I undertook to write down all the updates we anticipate in this issue so that nothing will come as surprise and be too late to be implemented. I'm now dubious as to the wisdom of the whole approach given that the JFET insulation fix tried to follow this route a week or two earlier and has run into solids.

Ideally this Annex should have been issued this week to fit in with IID-B issue 3.0 and some industry CDR sign-offs. However supply by sub-systems (including RAL) means I will issue it on 10th October. This means it's imperative that I have all the inputs by end of play on 9th.

The changes to be included are:

- a. DRCU's use of M5 fixing to SVM, and the webs between the feet for thermal conductance control. CEA has submitted RFD_CEA_SPIRE_FCU_n9.doc and RFD_CEA_SPIRE_FCU_n10.doc which have been processed and accepted.
- b. AVM DRCU drawings, already submitted, will be included here for completeness
- c. Spire FPU ICD issue 18 (minuted as clearing all Astrium comments on issue 17)
- d. JFET ICD updates
 - Include L3 interface arrangement/components
 - JPL's new back-harness layout and its hold-downs+ connector mounting
 - Corrected thermal insulation at feet
 - Some internal mass redistribution.

Please note folks that we should NOT include any other changes in this issue as trying to sort out unannounced variations would compromise the whole approach.

Two comments about the DPU. It comes in different versions and the mass of the Spire PFM unit is still subject to ~200 grams clarification. Spire has no plans to increase mass by making the unit black, which would be a change to the ICD, no-one having demonstrated that this is thermally necessary.

Cheers

John